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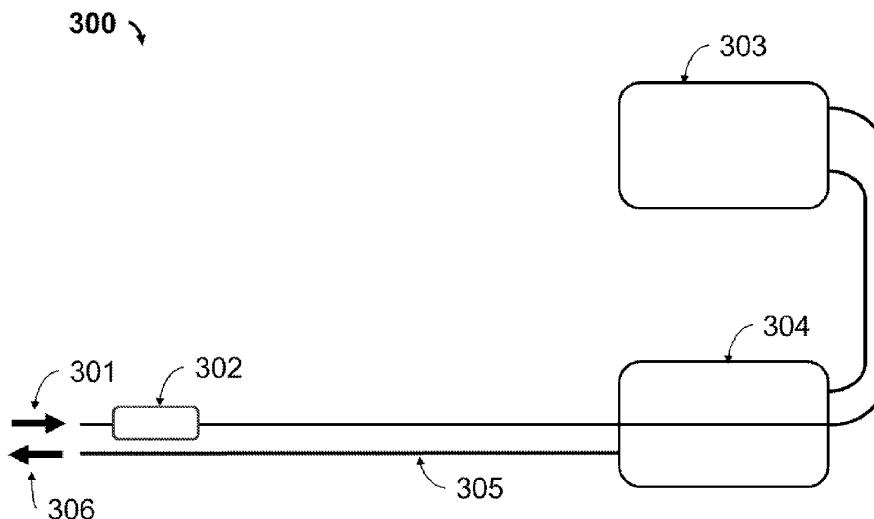


Figure 3

(57) Abstract: Apparatus, devices, systems, subsystems and methods for passively balancing and controlling coolant flow throughout complex fluidic pipe network to be implemented in electronics cooling applications. Systems, sub-systems, devices and methods for providing cooling to hardware components, and more specifically to control flow distribution between sub-systems, devices and methods for thermal management of hardware in server racks and any other hardware components or equipment for the information and communications technology (ICT) industry.

[Continued on next page]

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